

(Table 1)

| Example | Heat cycle test | | | | | Dissolu-tion of conductor circuit |
|--------------------------|---|-------------|--------------------|-------------|------------------|--|
| | Crack of interlaminar insulating resin layer | | Peeling of viahole | | Peel strength | |
| | 1000 cycles | 2000 cycles | 1000 cycles | 2000 cycles | | |
| 1 | none | none | none | none | 1.0kg/cm | presence |
| 2 | none | none | none | none | 1.0kg/cm | presence |
| 3 | none | none | none | none | 1.0kg/cm | none |
| 4 | none | none | none | none | 1.0kg/cm | none |
| 5 | none | none | none | none | 1.0kg/cm | none |
| 6-1 | none | none | none | none | 1.0kg/cm | none |
| 6-2 | none | none | none | none | 1.0kg/cm | none |
| 6-3 | none | none | none | none | 1.0kg/cm | none |
| 6-4 | none | none | none | none | 1.0kg/cm | none |
| 6-5 | none | none | none | none | 1.0kg/cm | none |
| 6-6 | none | none | none | none | 1.0kg/cm | none |
| 6-7 | none | none | none | none | 1.0kg/cm | none |
| 6-8 | none | none | none | none | 1.0kg/cm | none |
| 6-9 | none | none | none | none | 1.0kg/cm | none |
| 6-10 | none | none | none | none | 1.0kg/cm | none |
| Comparative Example 1 | none | presence | none | presence | 0.9kg/cm | presence |
| Comparative Example 2 | none | presence | none | presence | 0.9kg/cm | none |

Industrial Applicability

As mentioned above, according to the invention, it is possible to prevent the occurrence of cracks and the conductor peeling in the interlaminar insulating layer and dissolution of the conductor circuit due to the local electrode reaction, etc.